

## EXHIBIT A

1. (Original) Structure comprising:  
a generally planar workpiece carrier comprising at least one opening for holding a generally disk-shaped workpiece; and  
a ring movably placed within said at least one opening, said ring having a discontinuity therein.
2. (Original) Structure of claim 1 wherein said ring is rotatable within said opening.
3. (Original) Structure of claim 1 further comprising a workpiece within said opening and surrounded by said ring, wherein said workpiece can rotate with respect to said carrier.
4. (Original) Structure of claim 3 wherein said carrier is within polishing apparatus, said polishing apparatus comprising one or more pads for polishing said workpiece, said ring having a thickness such that said ring prevents or reduces roll-off in said workpiece.
5. (Original) Structure of claim 1 wherein said workpiece comprises a centrally defined opening therein, said structure further comprising a member inserted into said centrally defined opening.
6. (Currently amended) A combination of a workpiece and apparatus, wherein said workpiece has an opening therein and said apparatus comprises:

a generally planar workpiece carrier comprising at least one opening for holding said workpiece;

a member inserted into said opening of said workpiece; and

at least one polishing pad for polishing at least one surface of said workpiece, said polishing pad extending over said workpiece, said opening and said member.

7. (Currently amended) A combination of a workpiece and apparatus, wherein said workpiece has an opening therein and said apparatus comprises:

a generally planar workpiece carrier comprising at least one opening for holding said workpiece;

a member inserted into said opening of said workpiece; and

at least one polishing pad for polishing at least one surface of said workpiece

~~Combination of claim 6 wherein said member prevents or reduces roll-off near the opening of said workpiece, and wherein said member comprises either a disk or a first ring.~~

8. (Currently Amended) Combination of claim 6 wherein said member comprises either a disk or a first ring, said combination further comprising a second ring within the opening of said carrier and surrounding said workpiece.

9. (Original) Method comprising:

providing a structure comprising a generally planar workpiece carrier comprising at least one opening:

providing a ring within said at least one opening, said ring having a discontinuity therein;

placing a generally disk-shaped workpiece within said ring; and

polishing said workpiece by applying at least one polishing pad surface against said workpiece.

10. (Original) Method of claim 9 wherein said workpiece can rotate during polishing.

11. (Original) Method of claim 9 wherein said ring prevents or reduces roll-off in said workpiece during polishing.

12. (Original) Method of claim 9 wherein said polishing comprises applying two generally planar polishing pads against upper and lower surfaces of said workpiece, and applying a polishing slurry between said pads and said workpiece during polishing.

13. (Original) Method of claim 9 wherein said workpiece comprises a centrally defined opening therein, said structure further comprising a member inserted into said centrally defined opening.

14. (Previously presented) Method comprising:

providing a structure comprising a generally planar workpiece carrier comprising at least one opening;

placing a generally disk-shaped workpiece within said opening of said carrier,  
said workpiece having an opening therein;

providing a member within said opening of said workpiece; and

polishing said workpiece by applying at least one polishing pad against said  
workpiece, wherein said workpiece carrier, member and polishing pad act as at least a  
portion of polishing apparatus, said polishing pad extending over said workpiece, said  
opening and said member during at least part of said act of polishing.

15. (Currently amended) Method comprising:

providing a structure comprising a generally planar workpiece carrier comprising  
at least one opening;

placing a generally disk-shaped workpiece within said opening of said carrier,  
said workpiece having an opening therein;

providing a member within said opening of said workpiece; and

polishing said workpiece by applying at least one polishing pad against said  
workpiece, wherein said workpiece carrier, member and polishing pad act as at least a  
portion of polishing apparatus, of claim 14 wherein said member prevents or reduces roll-  
off of said workpiece, ~~said member comprising either a ring or a disk within the opening  
of said workpiece.~~

16. (Currently amended) Method of claim 14 wherein said member comprises either  
a first ring or a disk within the opening of said workpiece, said method further

comprising providing a second ring between said workpiece and said carrier, said second ring preventing or reducing roll-off in said workpiece during polishing.

17. (New) Structure of claim 1 wherein said workpiece is rotatable with respect to said ring.

18. (New) Structure comprising:

a generally planar workpiece carrier comprising at least one opening for holding a generally disk-shaped workpiece; and

a ring movably placed within said at least one opening, said ring having a break therein, wherein the material of said ring on one side of said break is not rigidly affixed to the material of said ring on the other side of said break.

19. (New) Structure of claim 18 wherein said break comprises a gap in said ring.

20. (New) Structure of claim 18 wherein material of said ring on one side of said break contacts the material of said ring on the other side of said break.

21. (New) Method of claim 9 wherein said workpiece is rotatable with respect to said ring.

22. (New) Method comprising:

providing a structure comprising a generally planar workpiece carrier comprising at least one opening:

providing a ring within said at least one opening, said ring having a break therein;

placing a generally disk-shaped workpiece within said ring; and

polishing said workpiece by applying at least one polishing pad surface against said workpiece, wherein material of said ring on one side of said break is not rigidly affixed to the material of said ring on the other side of said break.

23. (New) Method of claim 9 wherein said break comprises a gap in said ring.

24. (New) Method of claim 22 wherein the material of said ring on one side of said break contacts the material of said ring on the other side of said break.

## EXHIBIT B

**[0004]** At the conclusion of polishing, it would be desirable for the substrate 4 to have a profile as shown in cross-section in Fig. 2. Unfortunately, substrates often emerge from the polishing process with a defect called "roll-off", schematically shown by dotted ~~[[lines]]~~ line R in Fig. 3, which extends into the data zone 4z. (Data zone 4z is where data will ultimately be recorded on the disk when it is finished.) One cause of roll-off is that substrates 4 have a thickness T4 that is greater than thickness T2 of carrier 2. Therefore, pads 9, 10 tend to push harder against the edges E of substrates 4, thereby causing roll-off. It would be desirable to prevent roll-off.